

# TECNOPRENE® VK6HIT1

## TECNOPRENE®

Polypropylene, homopolymer. 31% glass fiber reinforced, chemically bonded, high flow, high heat stabilisation.

### Product information

Resin Identification	PP-GF31	ISO 1043
Part Marking Code	>PP-GF31<	ISO 11469

### Rheological properties

Melt mass-flow rate	13 g/10min	ISO 1133
Melt mass-flow rate, Temperature	230 °C	
Melt mass-flow rate, Load	2.16 kg	

### Typical mechanical properties

Tensile modulus	7000 MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	95 MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	3 %	ISO 527-1/-2
Flexural modulus	6500 MPa	ISO 178
Flexural strength	140 MPa	ISO 178
Charpy impact strength, 23°C	48 kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23°C	11.5 kJ/m <sup>2</sup>	ISO 179/1eA
Izod notched impact strength, 23°C	10 kJ/m <sup>2</sup>	ISO 180/1A
Poisson's ratio	0.35 <sup>[C]</sup>	

[C]: Calculated

### Thermal properties

Melting temperature, 10°C/min	165 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	148 °C	ISO 75-1/-2

### Flammability

Burning Behav. at thickness h	HB class	IEC 60695-11-10
Thickness tested	3.2 mm	IEC 60695-11-10
FMVSS Class	B	ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	73.3 mm/min	ISO 3795 (FMVSS 302)

### Electrical properties

Volume resistivity	>1E13 Ohm.m	IEC 62631-3-1
Surface resistivity	1E14 Ohm	IEC 62631-3-2
Electric strength	43 kV/mm	IEC 60243-1
Comparative tracking index, 100 drops	600	IEC 60112
Relative permittivity, printed circuits and boards, 2.5 GHz	2.7 <sup>[1]</sup>	IEC 61189-2-721
Relative permittivity, printed circuits and boards, 10 GHz	2.77	IEC 61189-2-721
Dissipation factor, printed circuits and boards, 2.5 GHz	26 <sup>[1]</sup> E-4	IEC 61189-2-721
Dissipation factor, printed circuits and boards, 10 GHz	31 E-4	IEC 61189-2-721

[1]: 1.9GHz

# TECNOPRENE® VK6HIT1

## TECNOPRENE®

### Physical/Other properties

Density

1140 kg/m<sup>3</sup>

ISO 1183

### Characteristics

Processing

Injection Moulding

Special characteristics

Heat stabilised or stable to heat, High Flow

### Additional information

Processing Notes

### Storage

This product should be stored in a covered facility and kept away from moisture and heat.